

EXHIBIT D.05
U.S. Patent No. 6,853,142

References cited herein:

- U.S. Pat. No. 6,853,142 (“’142 Patent”)
- D.V. Mozgrin, *et al*, High-Current Low-Pressure Quasi-Stationary Discharge in a Magnetic Field: Experimental Research, Plasma Physics Reports, Vol. 21, No. 5, 1995 (“Mozgrin”)
- U.S. Pat. No. 6,190,512 (“Lantsman”)
- D.V. Mozgrin, High-Current Low-Pressure Quasi-Stationary Discharge in a Magnetic Field: Experimental Research, Thesis at Moscow Engineering Physics Institute, 1994 (“Mozgrin Thesis”)
- Dennis M. Manos & Daniel L. Flamm, Plasma Etching: An Introduction, Academic Press 1989 (“Manos”)
- Milton Ohring, The Material Science of Thin Films, Academic Press, 1992 (“Ohring”)
- Donald L. Smith, Thin-Film Deposition: Principles & Practice, McGraw Hill, 1995 (“Smith”)
- Yu. P. Raizer, Gas Discharge Physics, Springer, 1991 (“Raizer”)

‘142 Claims 13 and 16	Mozgrin in view of Lantsman and Mozgrin Thesis
<p>[10pre.] A method for generating a strongly-ionized plasma in a chamber, the method comprising:</p>	<p>The combination of Mozgrin and Lantsman discloses a method for generating a strongly-ionized plasma in a chamber.</p> <p>‘142 Patent at claim 18 (“wherein the peak plasma density of the strongly-ionized plasma is greater than about 10^{12} cm^{-3}”)</p> <p>Mozgrin at Fig 1</p> <p>Mozgrin at 400, right col, ¶ 4 (“To study the high-current forms of the discharge, we used two types of devices: a planar magnetron and a system with specifically shaped hollow electrodes.”)</p> <p>Mozgrin at 401, right col, ¶2 (“For pre-ionization ... the initial plasma density in the $10^9 - 10^{11} \text{ cm}^{-3}$ range.”)</p> <p>Mozgrin at 409, left col, ¶ 4 (“The implementation of the high-current magnetron discharge (regime 2) in sputtering ... plasma density (exceeding $2 \times 10^{13} \text{ cm}^{-3}$).”)</p> <p>Mozgrin at 409, left col, ¶5 (“The high-current diffuse</p>

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	discharge (regime 3) is useful for producing large-volume uniform dense plasmas $n_i \cong 1.5 \times 10^{15} \text{ cm}^{-3} \dots$ ”).
<p>[10a.] ionizing a feed gas to form a weakly-ionized plasma that reduces the probability of developing an electrical breakdown condition in the chamber;</p>	<p>The combination of Mozgrin and Lantsman discloses ionizing a feed gas to form a weakly-ionized plasma that reduces the probability of developing an electrical breakdown condition in the chamber.</p> <p>‘142 Patent at 5:18-19 (“The weakly-ionized plasma is also referred to as a pre-ionized plasma.”)</p> <p>‘142 Patent at claim 17 (“wherein the peak plasma density of the <i>weakly-ionized plasma is less than about 10^{12} cm^{-3}</i>”)</p> <p>Mozgrin at Figs. 1, 2, 3, 6, 7</p> <p>Mozgrin at 402, right col, ¶2 (“Figure 3 shows typical voltage and current oscillograms.... Part I in the voltage oscillogram represents the voltage of the stationary discharge (pre-ionization stage).”)</p> <p>Mozgrin at 401, right col, ¶2 (“[f]or pre-ionization, we used a stationary magnetron discharge; ... provided the initial plasma density in the $10^9 - 10^{11} \text{ cm}^{-3}$ range.”)</p> <p>Mozgrin at 400, right col, ¶ 3 (“We investigated the discharge regimes in <i>various gas mixtures</i> at $10^{-3} - 10$ torr...”)</p> <p>402, ¶ spanning left and right cols (“We studied the high-current discharge in wide ranges of discharge current...and operating pressure...<i>using various gases (Ar, N₂, SF₆, and H₂)</i> or their mixtures of various composition...”)</p> <p>Mozgrin at 401, left col, ¶ 1 (“The [plasma] discharge had an annular shape and was <i>adjacent to the cathode.</i>”)</p> <p>Mozgrin at 406, right col, ¶3 (“pre-ionization was not necessary; however, in this case, the probability of discharge transferring to arc mode increased.”)</p> <p>Mozgrin at 400, left col, ¶ 3 (“Some experiments on magnetron systems of various geometry showed that discharge regimes <i>which do not transit to arcs</i> can be obtained even at high currents.”)</p>

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	<p><u>Background:</u></p> <p>Manos at 231 (“We shall ... [include] information on unipolar arcs. These are a problem...”)</p> <p>Manos at 237 (“When such an arc occurs, the metal object is melted at the arc spot. The metal is explosively released.... How does one prevent such an arc? There are several methods...”)</p>
<p>[10b.] supplying power to the weakly-ionized plasma by applying an electrical pulse across the weakly-ionized plasma, the electrical pulse having a magnitude and a rise-time that is sufficient to increase the density of the weakly-ionized plasma to generate a strongly-ionized plasma; and</p>	<p>The combination of Mozgrin and Lantsman discloses supplying power to the weakly-ionized plasma by applying an electrical pulse across the weakly-ionized plasma, the electrical pulse having a magnitude and a rise-time that is sufficient to increase the density of the weakly-ionized plasma to generate a strongly-ionized plasma.</p> <p>‘142 Patent at 1:41-43 (“Magnetron sputtering systems use magnetic fields that are shaped to trap and to concentrate secondary electrons, which are produced by ion bombardment of the target surface.”)</p> <p>‘142 Patent at 1:37-40 (“The plasma is replenished by electron-ion pairs formed by the collision of neutral molecules with secondary electrons generated at the target surface.”)</p> <p>Mozgrin at Figs. 1, 2, 3</p> <p>Mozgrin at 402, right col, ¶ 2 (“Part 1 in the voltage oscillogram represents the voltage of the stationary discharge (pre-ionization stage).”)</p> <p>Mozgrin at 401, right col, ¶ 1 (“Thus, the supply unit was made providing square voltage and current pulses with [rise] times (leading edge) of 5 – 60 μs...”)</p>
<p>[10c.] diffusing the strongly-ionized plasma with additional feed gas thereby allowing the strongly-ionized plasma to absorb additional energy from the power supply.</p>	<p>The combination of Mozgrin and Lantsman discloses diffusing the strongly-ionized plasma with additional feed gas thereby allowing the strongly-ionized plasma to absorb additional energy from the power supply.</p> <p>It would have been obvious to one of ordinary skill to continue to add the feed gas in Mozgrin during production of the strongly-ionized plasma (i.e., during either of regions 2 or 3). Such addition of the feed gas would have both diffused the</p>

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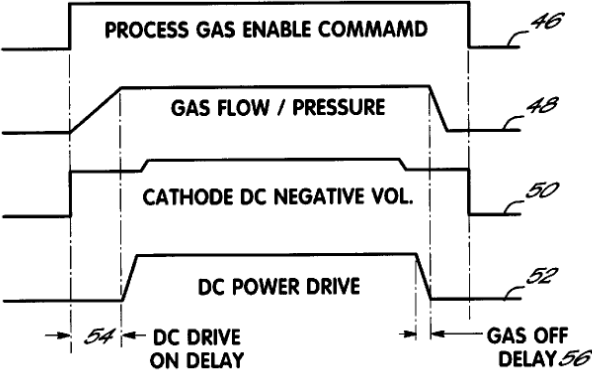
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	<p>strongly-ionized plasma and allowed additional power from Mozgrin’s repeating voltage pulses to be absorbed by the strongly-ionized plasma.</p> <p>‘142 Patent at 2:21-34 (“FIG. 1 illustrates a cross-sectional view of a known plasma generating apparatus 100.... A feed gas from feed gas source 109, such as an argon gas source, is introduced into the vacuum chamber 104 through a gas inlet 110. The gas flow is controlled by a valve 112.”)</p> <p>Mozgrin at Figs. 1 and 3</p> <p>Mozgrin at ¶ spanning pp. 403-404 (“The ... repetition frequency was 10 Hz....”).</p> <p>Mozgrin at 401, left col, ¶ 4 (“[A]pplying a square voltage pulse to the discharge gap which was filled up with either neutral or pre-ionized gas.”)</p> <p>Lantsman at Fig. 6</p>  <p align="right">FIG. 6</p> <p>Lantsman at 3:9-13 (“[A]t the beginning of processing, this switch is closed and gas is introduced into the chamber. When the plasma process is completed, the gas flow is stopped....”)</p> <p>Lantsman at 4:36-38 (“To end processing, primary supply 10 is disabled, reducing the plasma current and deposition on the wafer. Then, gas flow is terminated....”)</p> <p>Lantsman at 5:39-42 (“Sometime thereafter, gas flow is initiated and the gas flow and pressure (trace 48) begin to ramp upwards toward normal processing levels.”)</p>

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	<p>Lantsman at 5:42-45</p> <p>Lantsman at 2:48-51 (“This secondary power supply ‘pre-ignites’ the plasma so that when the primary power supply is applied, the system smoothly transitions to final plasma development and deposition.”)</p> <p>It would have been obvious to one of ordinary skill to continue to apply the feed gas during Mozgrin’s regions 1 and 2 as taught by Lantsman. Such a continuous introduction of feed gas balances gas withdrawn by the vacuum system (e.g., as shown in the drawings from Ohring and Smith, copied below) so as to maintain a desired pressure.</p> <p>One of ordinary skill would have been motivated to combine Mozgrin and Lantsman. Both Mozgrin and Lantsman are directed to sputtering using plasma. <i>See</i> Mozgrin at 409, left col, ¶ 4 (“The implementation of the high-current magnetron discharge (regime 2) in sputtering or layer-deposition technologies provides an enhancement in the flux of deposited materials and plasma density....”); <i>see also</i> Lantsman at 1:6-8 (“This invention relates to reduction of device damage in plasma processes, including DC (magnetron or non-magnetron) sputtering, and RF sputtering.”). Both references also relate to sputtering systems that use two power supplies, one for pre-ionization and one for deposition. <i>See</i> Lantsman at 4:45-47 (“[T]he secondary [power] supply 32 is used to pre-ignite the plasma, whereas the primary [power] supply 10 is used to generate deposition.”); <i>see</i> Mozgrin at Fig. 2. (<i>showing the “high-voltage supply unit” and the “stationary discharge supply unit”</i>)</p> <p>Moreover, both Mozgrin and Lantsman are concerned with generating plasma while avoiding arcing. <i>See</i> Mozgrin at 400, right col, ¶ 3 (“The main purpose of this work was to study experimentally a high-power noncontracted quasi-stationary discharge in crossed fields of various geometry and to determine their parameter ranges.”); <i>see also</i> Lantsman at 1:51-59 (“Furthermore, arcing which can be produced by overvoltages can cause local overheating of the target, leading to evaporation or flaking of target material into the processing chamber and causing substrate particle contamination and device damage.... Thus, it is advantageous to avoid voltage</p>

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